

**EH2520TTS-125.000M TR**
[Click part number to visit Part Number Details page](#)
**REGULATORY COMPLIANCE** (Data Sheet downloaded on Aug 28, 2016)
[Click badges to download compliance docs](#)

Regulatory Compliance standards are subject to updates by governing bodies. Click the badges to download the latest compliance docs for this part number directly from Ecliptek.

**ITEM DESCRIPTION**

Quartz Crystal Clock Oscillators XO (SPXO) HCMOS/TTL (CMOS) 5.0Vdc 4 Pad 5.0mm x 7.0mm Ceramic Surface Mount (SMD) 125.000MHz  $\pm 20$ ppm 0°C to +70°C

**ELECTRICAL SPECIFICATIONS**

<b>Nominal Frequency</b>	125.000MHz
<b>Frequency Tolerance/Stability</b>	$\pm 20$ ppm Maximum (Inclusive of all conditions: Calibration Tolerance at 25°C, Frequency Stability over the Operating Temperature Range, Supply Voltage Change, Output Load Change, First Year Aging at 25°C, Shock, and Vibration)
<b>Aging at 25°C</b>	$\pm 5$ ppm/year Maximum
<b>Operating Temperature Range</b>	0°C to +70°C
<b>Supply Voltage</b>	5.0Vdc $\pm 10\%$
<b>Input Current</b>	50mA Maximum (No Load)
<b>Output Voltage Logic High (Voh)</b>	2.4Vdc Minimum with TTL Load, Vdd-0.4Vdc Minimum with HCMOS Load (IOH= -16mA)
<b>Output Voltage Logic Low (Vol)</b>	0.4Vdc Maximum with TTL Load, 0.5Vdc Maximum with HCMOS Load (IOL= +16mA)
<b>Rise/Fall Time</b>	4nSec Maximum (Measured at 0.8Vdc to 2.0Vdc with TTL Load; Measured at 20% to 80% of waveform with HCMOS Load)
<b>Duty Cycle</b>	50 $\pm 5$ (%) (Measured at 50% of waveform with TTL Load or with HCMOS Load)
<b>Load Drive Capability</b>	5TTL Load or 15pF HCMOS Load Maximum
<b>Output Logic Type</b>	CMOS
<b>Pin 1 Connection</b>	Tri-State (High Impedance)
<b>Tri-State Input Voltage (Vih and Vil)</b>	+2.2Vdc Minimum to enable output, +0.8Vdc Maximum to disable output (High Impedance), No Connect to enable output.
<b>Absolute Clock Jitter</b>	$\pm 250$ pSec Maximum, $\pm 100$ pSec Typical
<b>One Sigma Clock Period Jitter</b>	$\pm 50$ pSec Maximum, $\pm 30$ pSec Typical
<b>Start Up Time</b>	10mSec Maximum
<b>Storage Temperature Range</b>	-55°C to +125°C

**ENVIRONMENTAL & MECHANICAL SPECIFICATIONS**

<b>ESD Susceptibility</b>	MIL-STD-883, Method 3015, Class 1, HBM: 1500V
<b>Fine Leak Test</b>	MIL-STD-883, Method 1014, Condition A
<b>Flammability</b>	UL94-V0
<b>Gross Leak Test</b>	MIL-STD-883, Method 1014, Condition C
<b>Mechanical Shock</b>	MIL-STD-883, Method 2002, Condition B
<b>Moisture Resistance</b>	MIL-STD-883, Method 1004
<b>Moisture Sensitivity</b>	J-STD-020, MSL 1
<b>Resistance to Soldering Heat</b>	MIL-STD-202, Method 210, Condition K
<b>Resistance to Solvents</b>	MIL-STD-202, Method 215
<b>Solderability</b>	MIL-STD-883, Method 2003
<b>Temperature Cycling</b>	MIL-STD-883, Method 1010, Condition B
<b>Vibration</b>	MIL-STD-883, Method 2007, Condition A

# EH2520TTS-125.000M TR [Click part number to visit Part Number Details page](#)

## MECHANICAL DIMENSIONS (all dimensions in millimeters)



PIN	CONNECTION
1	Tri-State
2	Ground
3	Output
4	Supply Voltage

LINE	MARKING
1	ECLIPTEK
2	125.00M
3	XXXXX XXXXX=Ecliptek Manufacturing Identifier

## Suggested Solder Pad Layout

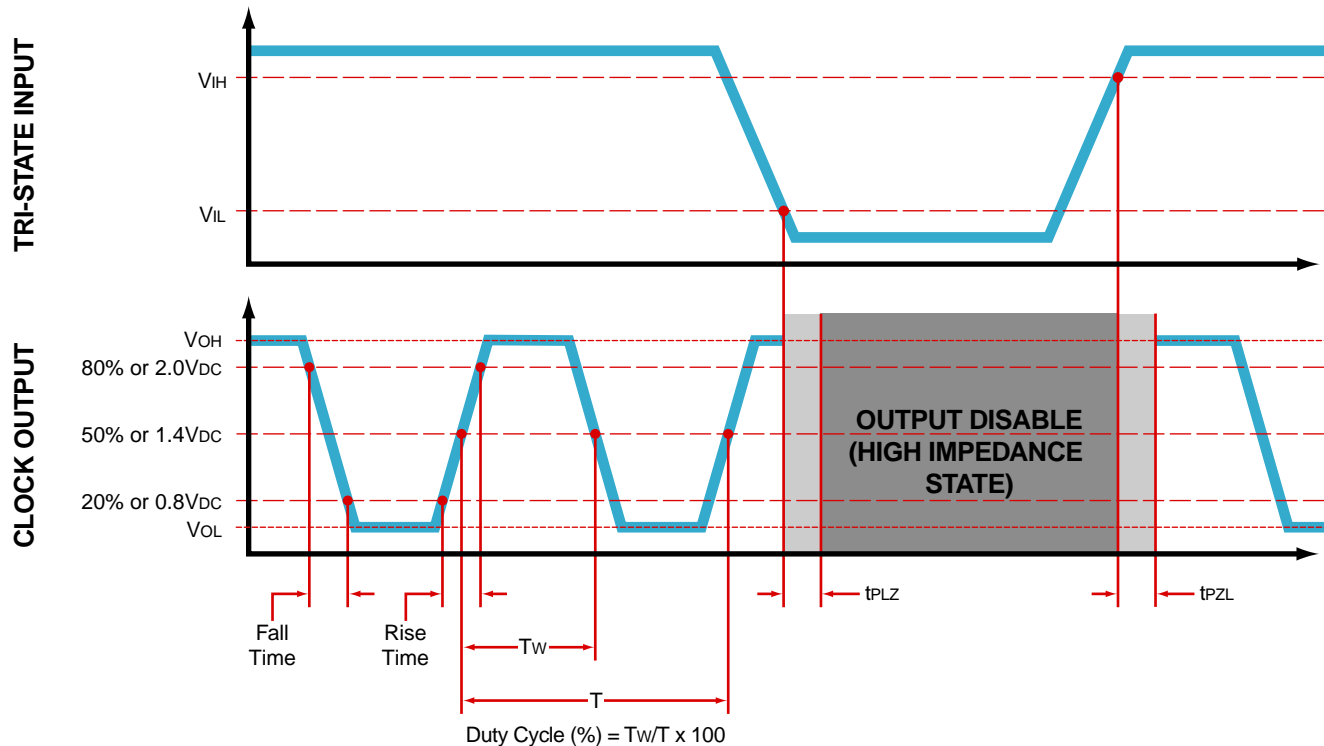
All Dimensions in Millimeters



All Tolerances are ±0.1

# EH2520TTS-125.000M TR [Click part number to visit Part Number Details page](#)

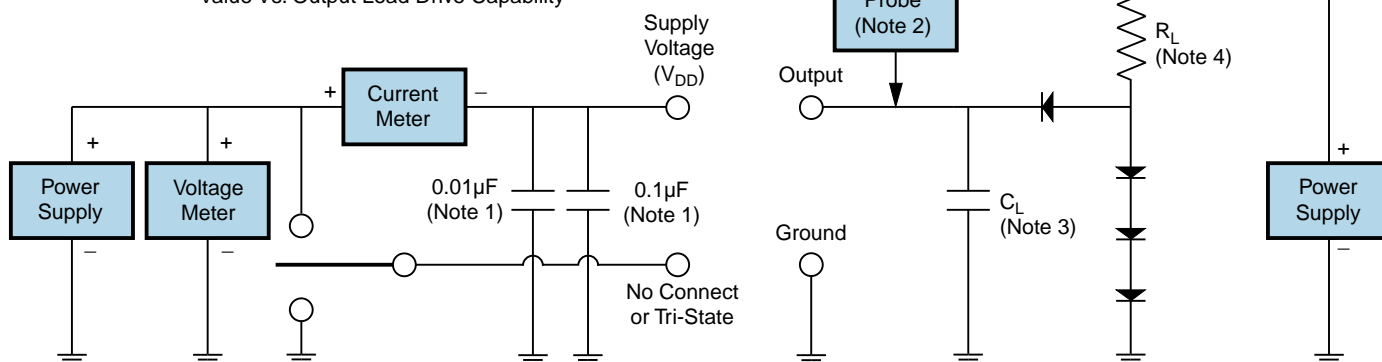
## OUTPUT WAVEFORM & TIMING DIAGRAM



## Test Circuit for TTL Output

Output Load Drive Capability	$R_L$ Value (Ohms)	$C_L$ Value (pF)
10TTL	390	15
5TTL	780	15
2TTL	1100	6
10LSTTL	2000	15
1TTL	2200	3

Table 1:  $R_L$  Resistance Value and  $C_L$  Capacitance Value Vs. Output Load Drive Capability



Note 1: An external 0.1µF low frequency tantalum bypass capacitor in parallel with a 0.01µF high frequency ceramic bypass capacitor close to the package ground and  $V_{DD}$  pin is required.

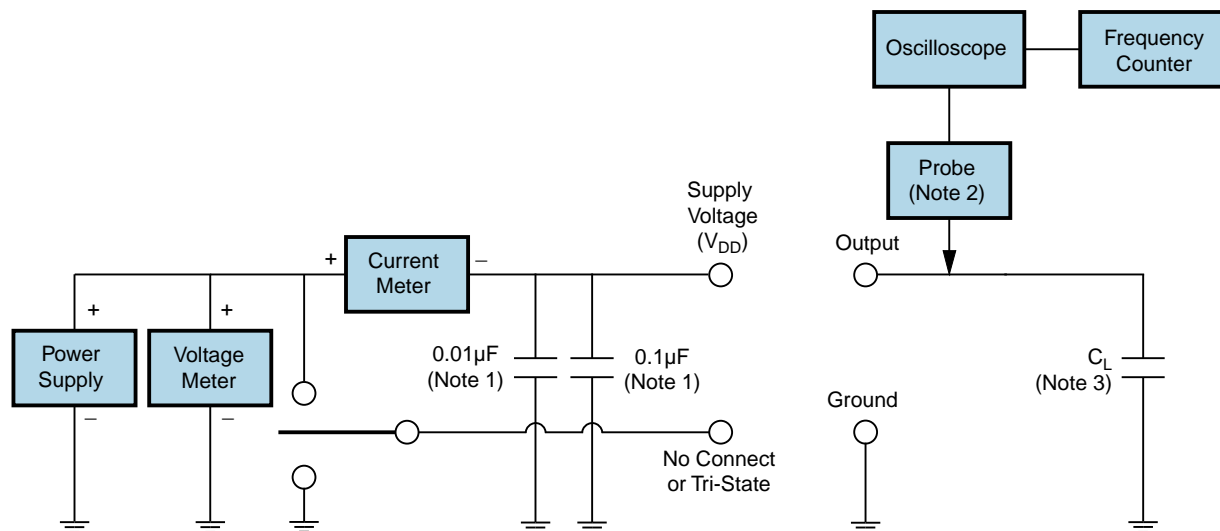
Note 2: A low capacitance (<12pF), 10X attenuation factor, high impedance (>10Mohms), and high bandwidth (>300MHz) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

Note 4: Resistance value  $R_L$  is shown in Table 1. See applicable specification sheet for 'Load Drive Capability'.

Note 5: All diodes are MMBD7000, MMBD914, or equivalent.

## Test Circuit for CMOS Output



Note 1: An external  $0.1\mu\text{F}$  low frequency tantalum bypass capacitor in parallel with a  $0.01\mu\text{F}$  high frequency ceramic bypass capacitor close to the package ground and  $V_{DD}$  pin is required.

Note 2: A low capacitance ( $<12\text{pF}$ ), 10X attenuation factor, high impedance ( $>10\text{Mohms}$ ), and high bandwidth ( $>300\text{MHz}$ ) passive probe is recommended.

Note 3: Capacitance value  $C_L$  includes sum of all probe and fixture capacitance.

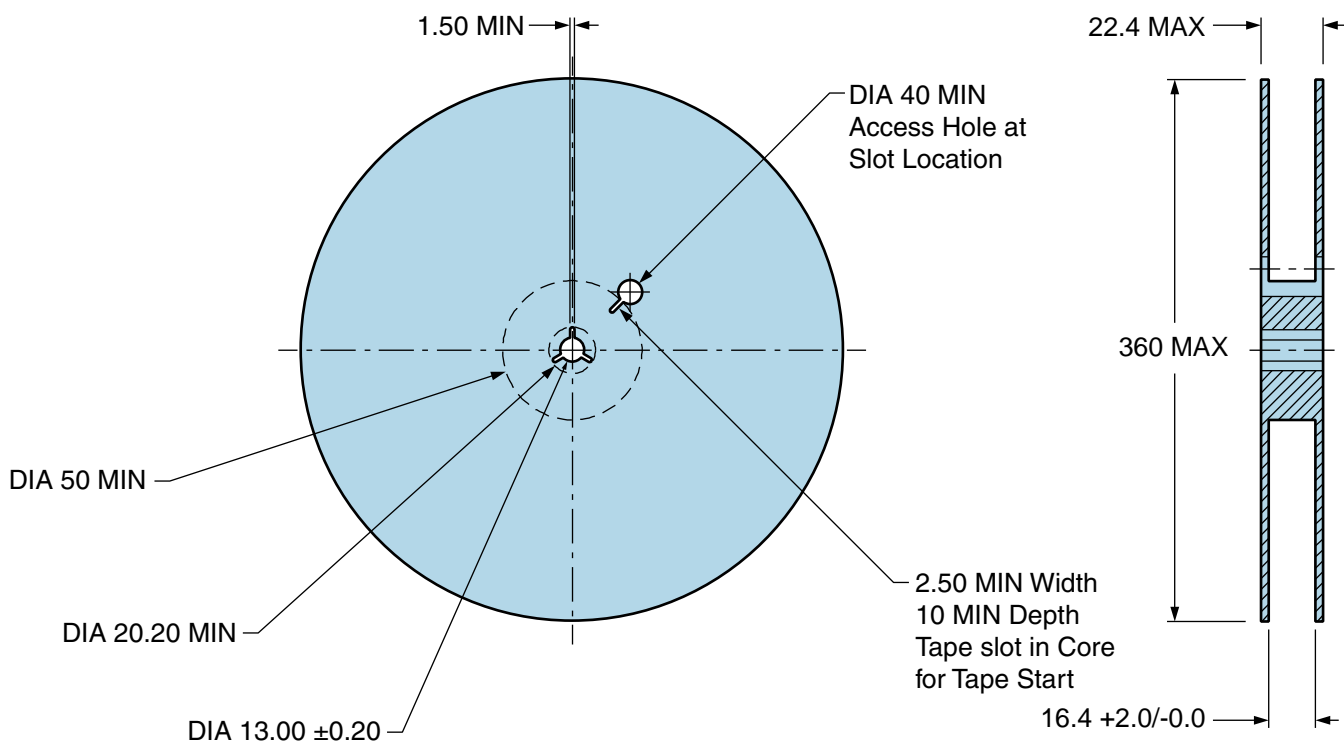
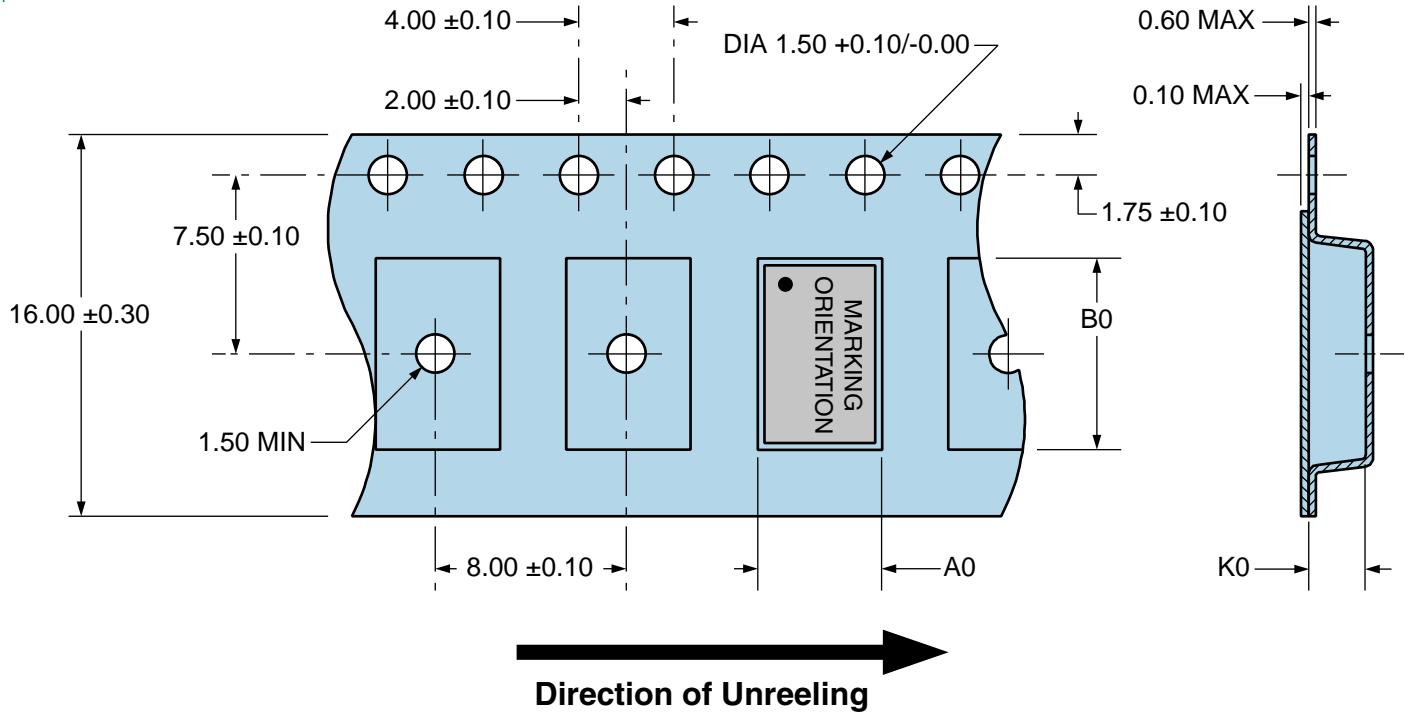
# EH2520TTS-125.000M TR

## Tape & Reel Dimensions

Quantity Per Reel: 1,000 units

All Dimensions in Millimeters

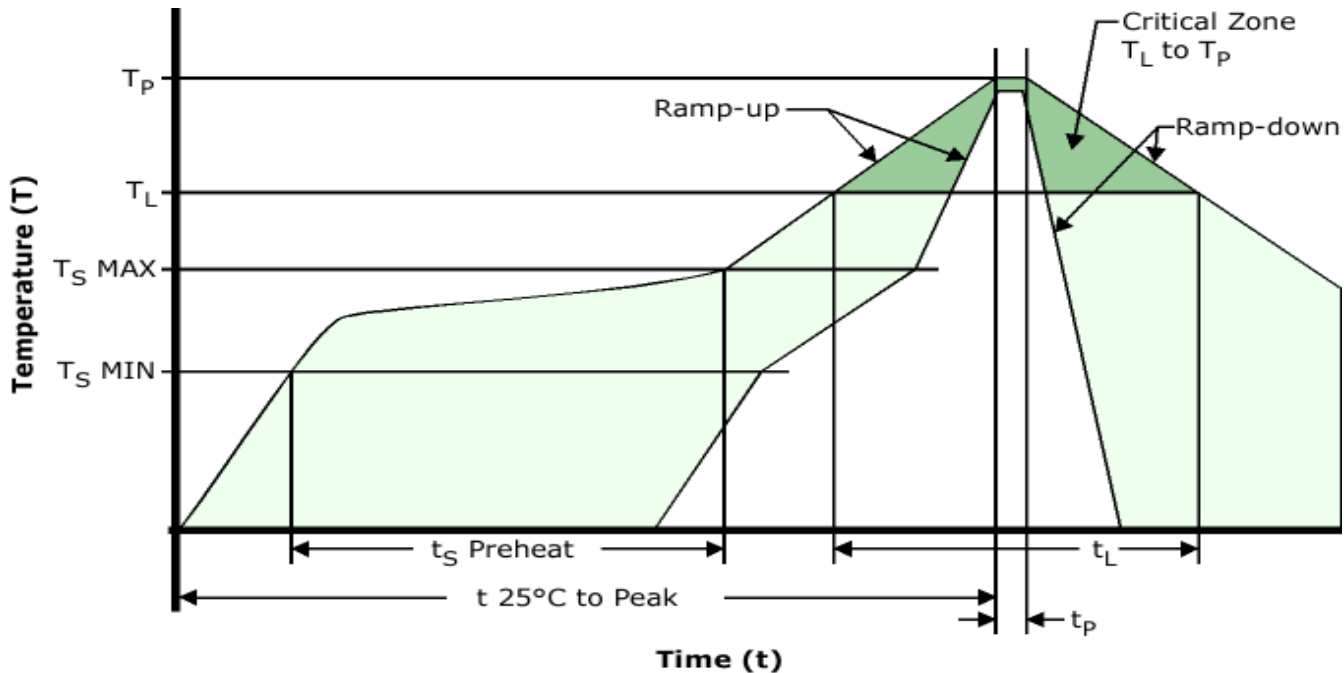
Compliant to EIA-481



# EH2520TTS-125.000M TR

[Click part number to visit Part Number Details page](#)

## Recommended Solder Reflow Methods



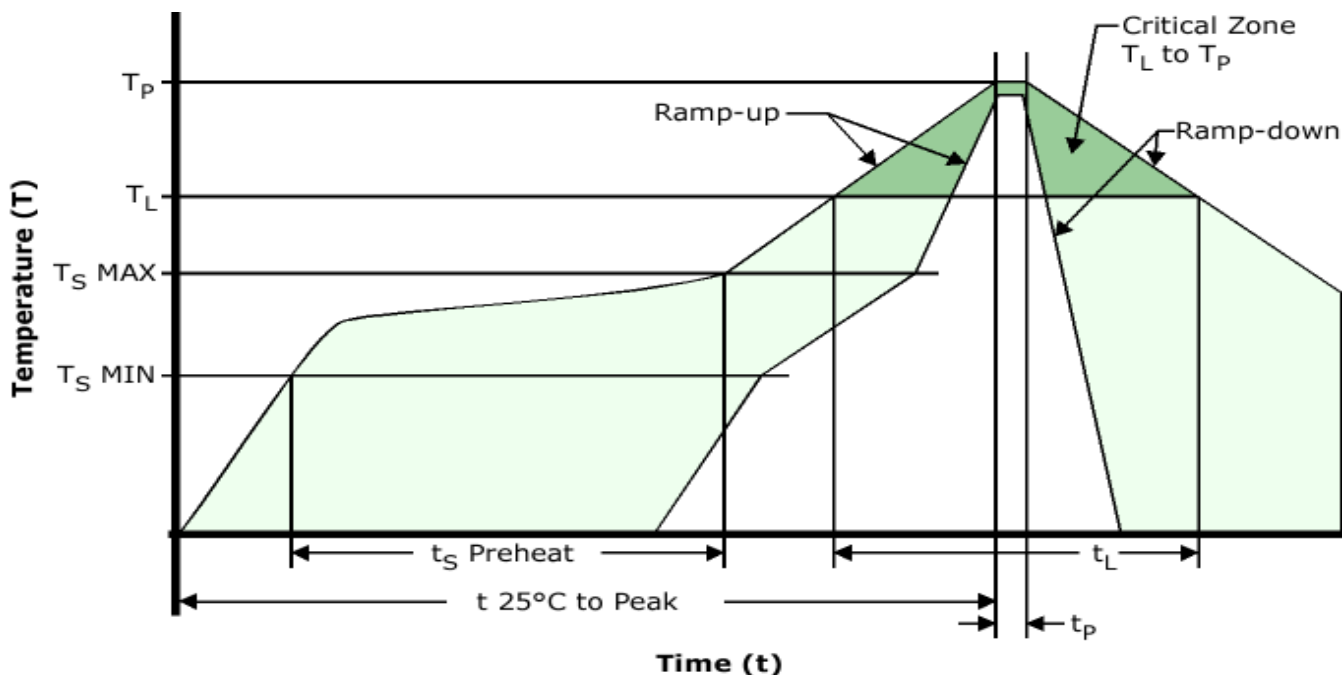
## High Temperature Infrared/Convection

<b><math>T_S</math> MAX to <math>T_L</math> (Ramp-up Rate)</b>	3°C/Second Maximum
<b>Preheat</b>	
- Temperature Minimum ( $T_S$ MIN)	150°C
- Temperature Typical ( $T_S$ TYP)	175°C
- Temperature Maximum ( $T_S$ MAX)	200°C
- Time ( $t_s$ MIN)	60 - 180 Seconds
<b>Ramp-up Rate (<math>T_L</math> to <math>T_P</math>)</b>	3°C/Second Maximum
<b>Time Maintained Above:</b>	
- Temperature ( $T_L$ )	217°C
- Time ( $t_L$ )	60 - 150 Seconds
<b>Peak Temperature (<math>T_P</math>)</b>	260°C Maximum for 10 Seconds Maximum
<b>Target Peak Temperature (<math>T_P</math> Target)</b>	250°C +0/-5°C
<b>Time within 5°C of actual peak (<math>t_p</math>)</b>	20 - 40 Seconds
<b>Ramp-down Rate</b>	6°C/Second Maximum
<b>Time 25°C to Peak Temperature (t)</b>	8 Minutes Maximum
<b>Moisture Sensitivity Level</b>	Level 1
<b>Additional Notes</b>	Temperatures shown are applied to body of device.

# EH2520TTS-125.000M TR

[Click part number to visit Part Number Details page](#)

## Recommended Solder Reflow Methods



### Low Temperature Infrared/Convection 240°C

Ts MAX to TL (Ramp-up Rate)	5°C/Second Maximum
-----------------------------	--------------------

#### Preheat

- Temperature Minimum (Ts MIN)	N/A
- Temperature Typical (Ts TYP)	150°C
- Temperature Maximum (Ts MAX)	N/A
- Time (ts MIN)	60 - 120 Seconds

Ramp-up Rate (TL to TP)	5°C/Second Maximum
-------------------------	--------------------

#### Time Maintained Above:

- Temperature (TL)	150°C
- Time (tL)	200 Seconds Maximum

Peak Temperature (TP)	240°C Maximum
-----------------------	---------------

Target Peak Temperature (TP Target)	240°C Maximum 2 Times / 230°C Maximum 1 Time
-------------------------------------	--

Time within 5°C of actual peak (tp)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time
-------------------------------------	--

Ramp-down Rate	5°C/Second Maximum
----------------	--------------------

Time 25°C to Peak Temperature (t)	N/A
-----------------------------------	-----

Moisture Sensitivity Level	Level 1
----------------------------	---------

Additional Notes	Temperatures shown are applied to body of device.
------------------	---

### Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)

### High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)